

Title (en)
WAFER SINGULATION PROCESS CONTROL

Title (de)
WAFERVEREINZELUNGSPROZESSSTEUERUNG

Title (fr)
COMMANDE DE PROCÉDÉ DE SÉPARATION DE TRANCHE

Publication
EP 3398204 A4 20190821 (EN)

Application
EP 16882467 A 20161223

Priority
• US 201562272876 P 20151230
• US 2016068519 W 20161223

Abstract (en)
[origin: WO2017117051A1] A method for monitoring and controlling a substrate singulation process is described. Device edges are imaged and identified for analysis. Discrepancies in device edges are noted and used to modify a singulation process and to monitor the operation of singulation processes for anomalous behavior.

IPC 8 full level
H01L 21/78 (2006.01); **H01L 21/02** (2006.01); **H01L 21/66** (2006.01); **H01L 21/76** (2006.01); **H01L 21/764** (2006.01)

CPC (source: EP KR US)
G06T 7/001 (2013.01 - US); **G06T 7/13** (2016.12 - US); **H01L 21/02021** (2013.01 - KR); **H01L 21/76** (2013.01 - KR); **H01L 21/764** (2013.01 - KR); **H01L 21/78** (2013.01 - EP KR US); **H01L 22/12** (2013.01 - EP US); **H01L 22/20** (2013.01 - EP US); **G06T 7/33** (2016.12 - US); **G06T 7/55** (2016.12 - US); **G06T 7/74** (2016.12 - US); **G06T 2207/20212** (2013.01 - US); **G06T 2207/30148** (2013.01 - US)

Citation (search report)
• [XYI] US 6192289 B1 20010220 - GEFFEN MICHAEL [IL], et al
• [Y] US 9165832 B1 20151020 - PAPANU JAMES S [US], et al
• [A] US 5710825 A 19980120 - SUDA KOUICHI [JP]
• [A] JP H05326700 A 19931210 - DISCO ABRASIVE SYSTEMS LTD
• [A] JP H06326187 A 19941125 - TOKYO SEIMITSU CO LTD
• [A] JP H03236260 A 19911022 - SUMITOMO ELECTRIC INDUSTRIES
• See references of WO 2017117051A1

Designated contracting state (EPC)
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

DOCDB simple family (publication)
WO 2017117051 A1 20170706; CN 108701650 A 20181023; EP 3398204 A1 20181107; EP 3398204 A4 20190821; JP 2019500754 A 20190110; JP 6966448 B2 20211117; KR 20180089543 A 20180808; SG 11201805283U A 20180730; TW 201737303 A 20171016; TW I713083 B 20201211; US 11315832 B2 20220426; US 2019019728 A1 20190117

DOCDB simple family (application)
US 2016068519 W 20161223; CN 201680080297 A 20161223; EP 16882467 A 20161223; JP 2018532444 A 20161223; KR 20187021613 A 20161223; SG 11201805283U A 20161223; TW 105143386 A 20161227; US 201616067748 A 20161223